

## SOT-89 N Channel Enhancement 沟道增强型 MOS Field Effect Transistor 场效应管

### ■ Features 特点

Low on-resistance 低导通电阻

$R_{DS(ON)}=13m\Omega$ (Type)@ $V_{GS}=10V$

$R_{DS(ON)}=16.5m\Omega$ (Type)@ $V_{GS}=4.5V$

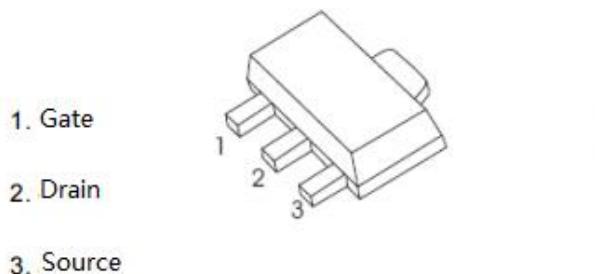
### ■ Applications 应用

Motor Drive 马达驱动

DC-DC Conversion 升压转换

Power Management 电源管理

### ■ Internal Schematic Diagram 内部结构



### ■ Absolute Maximum Ratings 最大额定值

Characteristic 特性参数	Symbol 符号	Rating 额定值	Unit 单位
Drain-Source Voltage 漏极-源极电压	$BV_{DSS}$	60	V
Gate- Source Voltage 栅极-源极电压	$V_{GS}$	$\pm 20$	V
Drain Current (continuous)漏极电流-连续	$I_D$ (at $T_A = 25^\circ C$ at $T_A = 100^\circ C$ )	40 33	A
Drain Current (pulsed)漏极电流-脉冲	$I_{DM}$	100	A
Total Device Dissipation 总耗散功率	$P_{TOT}$ (at $T_A = 25^\circ C$ at $T_A = 100^\circ C$ )	25 13	W
Thermal Resistance Junction-Case 热阻	$R_{\theta JC}$	2.3	$^\circ C/W$
Thermal Resistance Junction-Ambient 热阻	$R_{\theta JA}$	50	$^\circ C/W$
Avalanche Energy Single Pulse 雪崩能量	$E_{AS}$	49	mJ
Junction/Storage Temperature 结温/储存温度	$T_J, T_{stg}$	-55~150	$^\circ C$



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FS40N06F

## ■ Electrical Characteristics 电特性

( $T_A=25^\circ\text{C}$  unless otherwise noted 如无特殊说明, 温度为  $25^\circ\text{C}$ )

Characteristic 特性参数	Symbol 符号	Min 最小值	Typ 典型值	Max 最大值	Unit 单位
Drain-Source Breakdown Voltage 漏极-源极击穿电压( $I_D=250\mu\text{A}, V_{GS}=0\text{V}$ )	$\text{BV}_{\text{DSS}}$	60	—	—	V
Gate Threshold Voltage 栅极开启电压( $I_D=250\mu\text{A}, V_{GS}=V_{DS}$ )	$V_{GS(\text{th})}$	1.1	1.5	2.2	V
Zero Gate Voltage Drain Current 零栅压漏极电流( $V_{GS}=0\text{V}, V_{DS}=60\text{V}$ )	$I_{\text{DSS}}$	—	—	100	nA
Gate Body Leakage 栅极漏电流( $V_{GS}=\pm20\text{V}, V_{DS}=0\text{V}$ )	$I_{GSS}$	—	—	$\pm 100$	nA
Static Drain-Source On-State Resistance 静态漏源导通电阻( $I_D=20\text{A}, V_{GS}=10\text{V}$ ) ( $I_D=10\text{A}, V_{GS}=4.5\text{V}$ )	$R_{DS(\text{ON})}$	—	13 16.5	18 23	$\text{m}\Omega$
Diode Forward Voltage Drop 内附二极管正向压降( $I_{SD}=15\text{A}, V_{GS}=0\text{V}$ )	$V_{SD}$	—	0.8	1.2	V
Input Capacitance 输入电容 ( $V_{GS}=0\text{V}, V_{DS}=30\text{V}, f=1\text{MHz}$ )	$C_{ISS}$	—	2585	—	pF
Common Source Output Capacitance 共源输出电容( $V_{GS}=0\text{V}, V_{DS}=30\text{V}, f=1\text{MHz}$ )	$C_{OSS}$	—	150	—	pF
Reverse Transfer Capacitance 反馈电容( $V_{GS}=0\text{V}, V_{DS}=30\text{V}, f=1\text{MHz}$ )	$C_{RSS}$	—	78	—	pF
Total Gate Charge 棚极电荷密度 ( $V_{DS}=30\text{V}, I_D=20\text{A}, V_{GS}=10\text{V}$ )	$Q_g$	—	51	—	nC
Gate Source Charge 棚源电荷密度 ( $V_{DS}=30\text{V}, I_D=20\text{A}, V_{GS}=10\text{V}$ )	$Q_{gs}$	—	10	—	nC
Gate Drain Charge 棚漏电荷密度 ( $V_{DS}=30\text{V}, I_D=20\text{A}, V_{GS}=10\text{V}$ )	$Q_{gd}$	—	10	—	nC
Turn-ON Delay Time 开启延迟时间 ( $V_{DS}=30\text{V} I_D=20\text{A}, R_{\text{GEN}}=3\ \Omega, V_{GS}=10\text{V}$ )	$t_{d(\text{on})}$	—	11	—	ns
Turn-ON Rise Time 开启上升时间 ( $V_{DS}=30\text{V} I_D=20\text{A}, R_{\text{GEN}}=3\ \Omega, V_{GS}=10\text{V}$ )	$t_r$	—	25	—	ns
Turn-OFF Delay Time 关断延迟时间 ( $V_{DS}=30\text{V} I_D=20\text{A}, R_{\text{GEN}}=3\ \Omega, V_{GS}=10\text{V}$ )	$t_{d(\text{off})}$	—	89	—	ns
Turn-OFF Fall Time 关断下降时间 ( $V_{DS}=30\text{V} I_D=20\text{A}, R_{\text{GEN}}=3\ \Omega, V_{GS}=10\text{V}$ )	$t_f$	—	79	—	ns

## ■ Typical Characteristic Curve 典型特性曲线

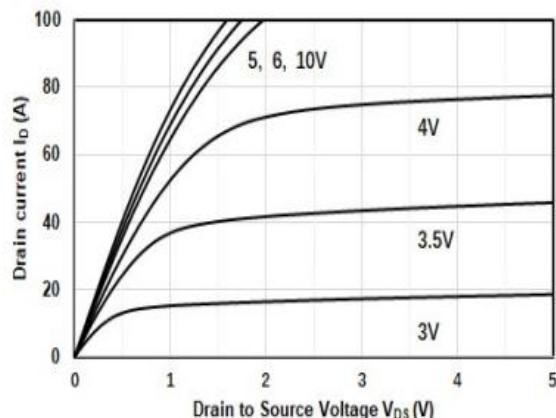


Figure 1: Output Characteristics

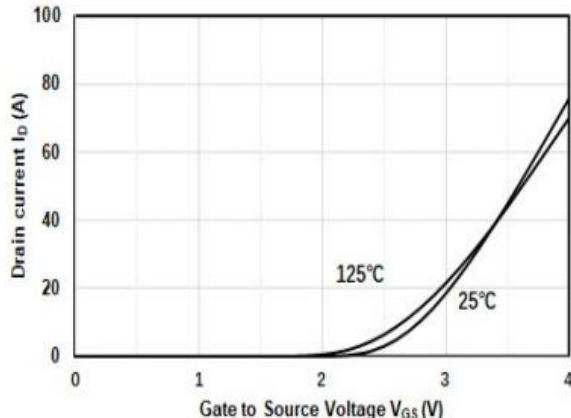


Figure 2: Transfer Characteristics

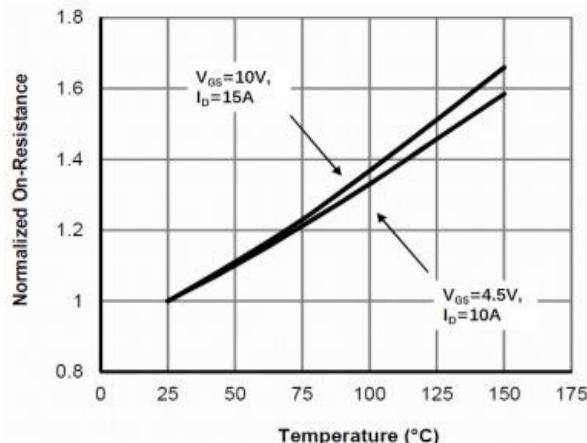


Figure 3: On-Resistance vs.  $T_J$

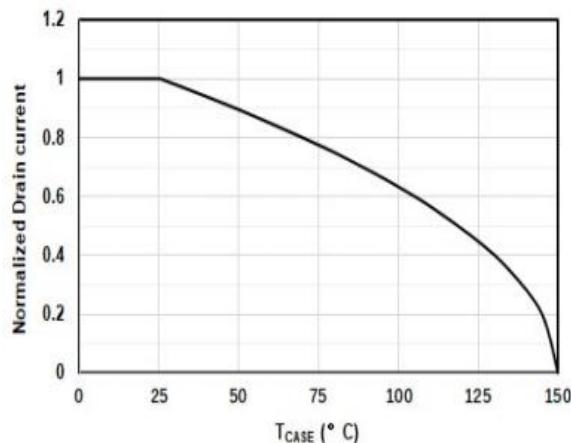


Figure 4: Drain Current vs. Temperature

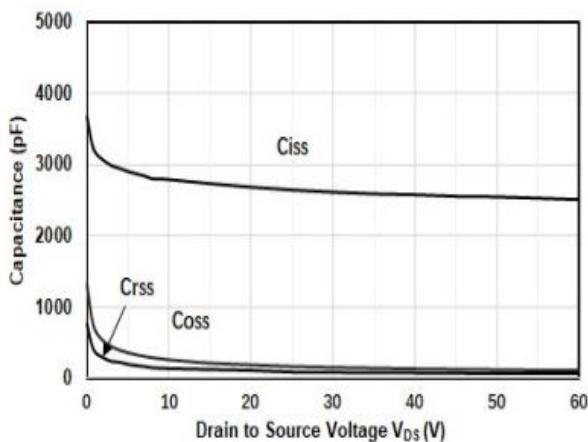


Figure 5: Capacitance Characteristics

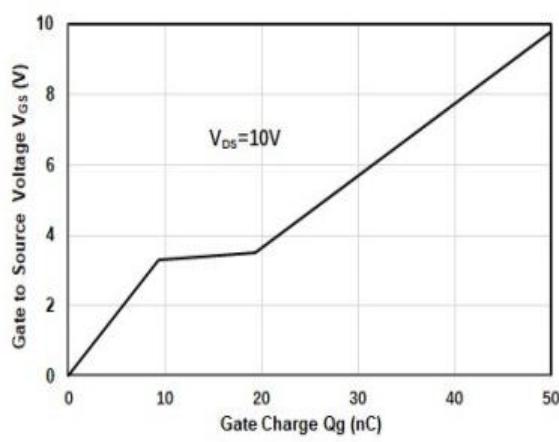


Figure 6: Gate-Charge Characteristics

## ■ Typical Characteristic Curve 典型特性曲线

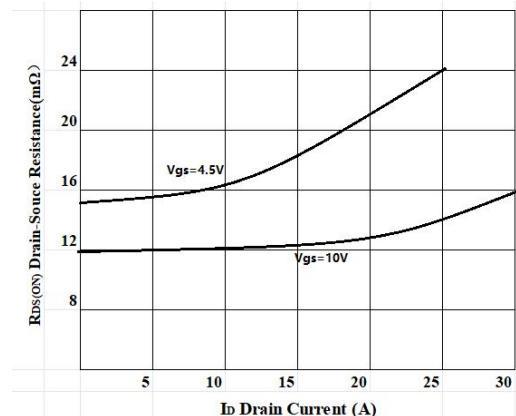


Figure 7: On-Resistance vs. Drain Current

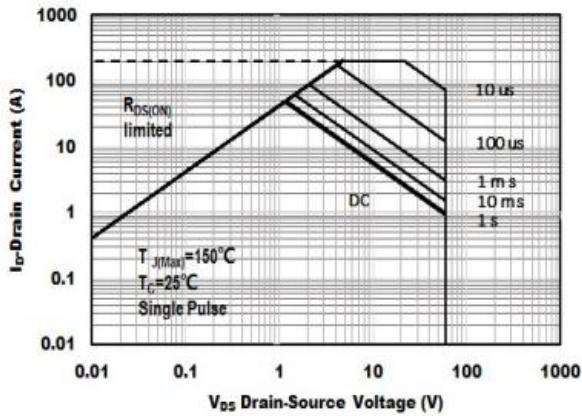


Figure 8: Safe Operating Area

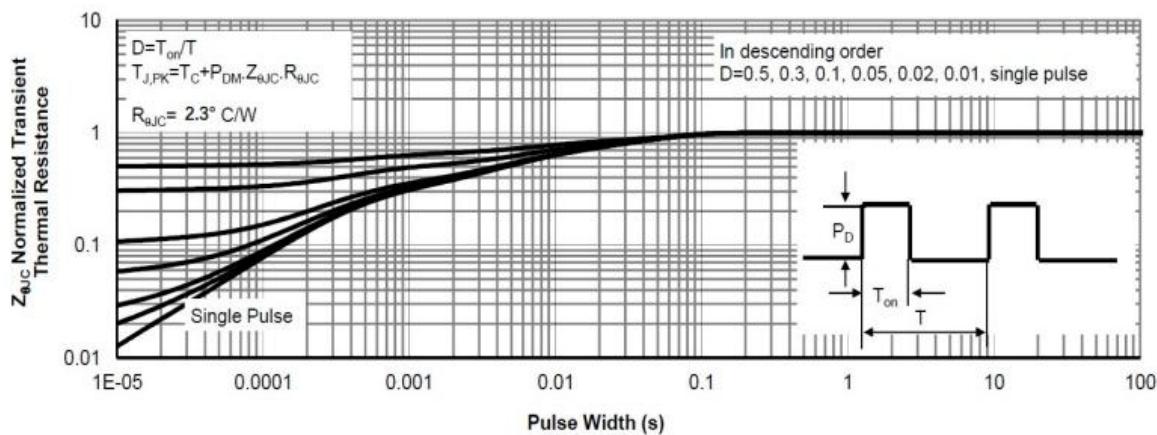
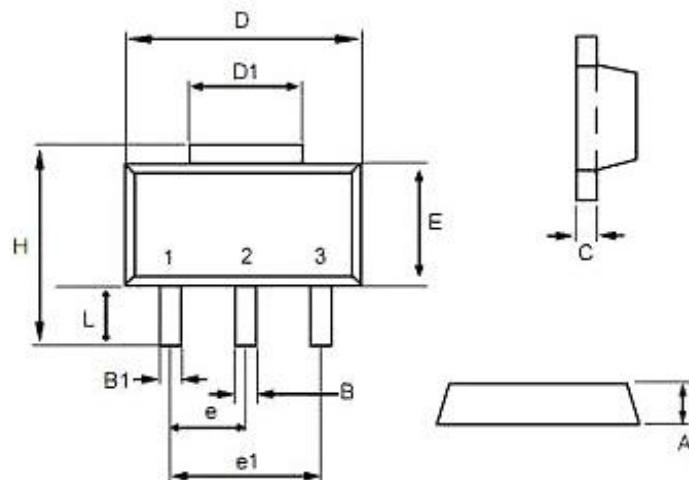


Figure 9: Transient Thermal Response Curve

■ Dimension 外形封装尺寸



Dim	min	max
A	1.40	1.60
B	0.40	0.56
B1	0.35	0.48
C	0.35	0.44
D	4.40	4.60
D1	1.35	1.83
e	1.50 BSC	
e1	3.00 BSC	
E	2.29	2.60
H	3.75	4.25
L	0.80	1.20